

## **REMARKS**

Applicant respectfully requests consideration of the subject application as amended herein. This Amendment is submitted in response to the Final Office Action mailed on April 20, 2005 and concurrently with a Request for Continued Examination. Claims 23-36, 61-98, 103 and 104 have been canceled without prejudice. Claims 1 and 22 have been amended. Claims 105-111 have been added. Claims 1-22, 37-60 and 99-102 are rejected per the Final Office Action. Applicant submits that no new matter has been added.

### **35 U.S.C. § 102(e)**

Claims 1-3, 5, 6, 8, 13, 19, 20, 22, 37, 38, 40-42, 48, 53, 56 and 60 are rejected under 35 U.S.C. § 102(e) as being anticipated by Kayanakis, et al, (U.S. Patent No. 6,536,674, hereinafter "Kayanakis").

Applicant respectfully disagrees. Kayanakis does not teach or suggest a thin-film dielectric layer. The Examiner analogizes Kayanakis' PVC layer 34 to the claims thin-film dielectric layer. However, as detailed in column 3, lines 27-30 of Kayanakis, the PVC layer 34 is approximately 80 microns thick. Our Specification at paragraph [057] provides an example of a thick film insulate 930 that has a thickness on the order of 10 microns. Accordingly, the PVC layer 34 cannot be a thin film dielectric layer as claimed by Applicant.

Additionally, the Examiner analogized conductive glue 42 of Kayanakis as Applicant's claimed conductive medium. However, the conductive glue 42 is not formed

over a dielectric layer that is formed over a portion of an integrated circuit and a portion of the substrate.

Moreover, in the currently amended form, the claimed conductive medium has a greater surface area than the conductive pad. This feature would allow for the easy integration of small-feature-size components (e.g., IC chips with large-feature-size components (e.g., antenna). Supports for these features can be found in many of the figures of Applicant's disclosure, e.g., Figure 1. Kayanakis did not discuss or even suggest such feature.

Moreover, in the currently amended form, the claimed second substrate is larger than the first substrate. See, for example, Figure 12A of Applicant's Specification for the support for this feature. As taught by Kayanakis, the antenna support 28 and the PVC layer 32 are of equal size and as such Kayanakis could have not suggested or taught the claimed feature above.

Therefore, Applicant respectfully submits that Kayanaki does not anticipate claims 1-3, 5, 6, 8, 13, 19, 20, 22, 37, 38, 40-42, 48, 53, 56 and 60. Furthermore, Applicant respectfully submits that Kayanaki does not anticipate the newly added claims 105-111 for the same reasons stated above.

**35 U.S.C. § 103(a)**

Claims 4, 39, 43 and 46 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Kayanakis, in view of Golwalkar, et al. (U.S. Patent Application No. 2002/0114587, hereinafter "Golwalkar").

Applicant respectfully disagrees.

As discussed above, Kayanakis does not teach or suggest a thin-film dielectric layer. Additionally, the Examiner analogized conductive glue 42 of Kayanakis as Applicant's claimed conductive medium. However, the conductive glue 42 is not formed over a dielectric layer that is formed over a portion of an integrated circuit and a portion of the substrate. Moreover, in the currently amended form, the claimed conductive medium has a greater surface area than the conductive pad. This feature would allow for the easy integration of small-feature-size components (e.g., IC chips with large-feature-size components (e.g., antenna). Kayanakis did not discuss or even suggest such feature.

Moreover, in the currently amended form, the claimed second substrate is larger than the first substrate. As taught by Kayanakis, the antenna support 28 and the PVC layer 32 are of equal size and as such Kayanakis could have not suggested or taught the claimed feature above.

Therefore, Applicant respectfully submits that combining Kayanaki and Golwalkar could have not derived to claims 4, 39, 43 and 46 and even newly added claims 105-111.

According to the reasons discussed above, Applicant respectfully requests the Examiner to withdraw the pending rejections.

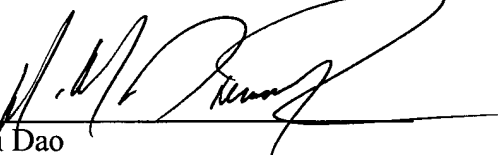
If the Examiner finds any remaining impediment to the prompt allowance of these claims that could be clarified with a telephone conference, Applicant respectfully requests the Examiner to contact Mimi Diemmy Dao at (408) 720-8300.

**Deposit Account Authorization**

Authorization is hereby given to charge our Deposit Account No. 02-2666 for any charges that may be due.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

  
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